



PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN Number: **22021A (Addendum)**

Date Issued: **8/11/2022**

Product(s) Affected:

| | | | |
|----------------|----------------|----------------|----------------|
| SP3072EEN-L | SP3072EEN-L/TR | SP3072EMN-L/TR | SP3075EEN-L |
| SP3075EEN-L/TR | SP3078EEN-L | SP3078EEN-L/TR | SP3078EMN-L/TR |
| SP3082EEN-L | SP3082EEN-L/TR | SP3085EEN-L | SP3085EEN-L/TR |
| SP3088EEN-L | SP3088EEN-L/TR | SP4082EEN-L/TR | SP1486EEN-L/TR |

Manufacturing Location Affected: Wafer foundry: Key Foundry, Korea
 Assembly: Greatek, Taiwan

Date Effective (90 day window): July 14, 2022

Date Issued +90 days: October 14, 2022

Means of Distinguishing Changed Devices:

- Product Mark: Lot number
- Back Mark
- Date Code
- Other

Contact: Your local MaxLinear Marketing Representative or contact our Customer Support team by creating a Support Ticket at <http://www.maxlinear.com/support/createcase>

Phone: 1-760-692-0711

Attachment: Yes No

Samples: **Request from MaxLinear Marketing Representatives**

Description and Purpose of Change:

MaxLinear has qualified Key Foundry wafer foundry in order to increase production capacity and to facilitate long term support of the product line. The wafer process is 0.18um BCD. The process has been optimized to produce very similar product characteristics as the currently shipping devices from TSMC foundry and will meet existing datasheet specifications.

Greatek is qualified for assembly of 8L NSOIC packages and is added as a supplier to the devices included in this notice.

There are no changes in device reliability

Note: Users who rely on DC, diode characteristics during ICT testing should take caution certain I/O characteristics may appear changed due to the proprietary I/O structures employed by Key Foundry. These DC / diode characteristic differences are not guaranteed nor required to ensure full design functionality per datasheet. Adjustments at ICT testing may be required to prevent false failures.

08/03/2022 Addendum:

Checked the "Manufacturing Site" box on the right sidebar

- Die Technology
- Wafer Fabrication
- Assembly Process
- Equipment
- Material
- Testing
- Product Design
- Manufacturing Site**
- Data Sheet
- Yield Enhancement
- Software
- Other:

Reliability/Qualification Summary: Reliability report available upon request



Customer Acknowledgement of Receipt within 30 days of issue. Lack of acknowledgement within 30 days constitutes acceptance of change.

Please fax or email this form to the contact above after completing the following information:

Customer: _____ Name: _____

Title: _____ Date: _____

E-Mail: _____ Phone: _____

Fax: _____

Approval for shipments prior to effective date

Customer Comments (Optional):